Tentative

DRC4514E				
Total pages	page			

DRC4514E

Silicon NPN epitaxial planar type

For digital circuits

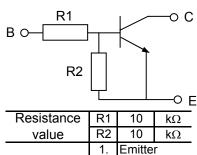
Marking Symbol: V6

Package Code: NS-B1-B

Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	VCBO	50	V
Collector-emitter voltage (Base open)	VCEO	50	V
Collector current	IC	500	mA
Total power dissipation	PT	300	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Internal Connection



Collector Base

Pin name

Electrical Characteristics Ta = 25 °C±3 °C

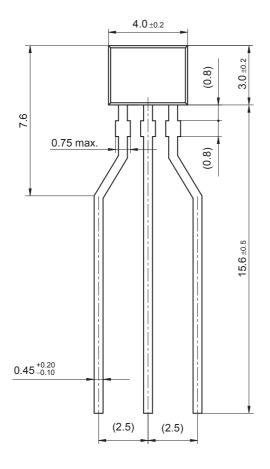
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	VCBO	IC = 10 μA, IE = 0	50			V
Collector-emitter voltage (Base open)	VCEO	IC = 2 mA, IB = 0	50			V
Collector-base cutoff current (Emitter open)	ICBO	VCB = 50 V, IE = 0			1	μA
Collector-emitter cutoff current (Base open)	ICEO	VCE = 50 V, IB = 0			1	μA
Emitter-base cutoff current (Collector open)	IEBO	VEB = 6 V, IC = 0			1	mA
Forward current transfer ratio	hFE	VCE = 10 V, IC = 100 mA	60			-
Collector-emitter saturation voltage	VCE(sat)	IC = 100 mA, IB = 5 mA			0.25	V
Input voltage	Vi(on)	VCE = 0.2 V, IC = 50 mA	5.7			V
input voltage	Vi(off)	VCE = 5 V, IC = 100 μA			0.7	V
Input resistance	R1		-30%	10	+30%	kΩ
Resistance ratio	R1/R2		0.8	1.0	1.2	-

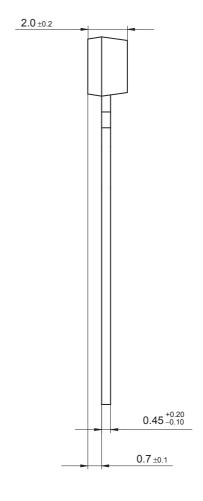
Note: Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

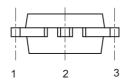
Packing

Radial type: 5000pcs / 1carton

NS-B1-B Unit: mm







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